



| ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TO-92 | | | | | |
|---|--------------------|-----------------------|-------------------|--------------------|------------------------|
| STRESS | SAMPLE SIZE | DEVICE HR./CYC | CONDITION | TOTAL FAILS | FAIL PERCENTAGE |
| BOND INT | 120 | 90 000 | 200 °C + N2 | 0 | 0.00 |
| HAST | 320 | 29 250 | 130 °C, 85 % RH | 0 | 0.00 |
| Pressure Pot | 620 | 59 520 | 121°, 15 PSIG | 0 | 0.00 |
| Solderability | 98 | 484 | 883 M2003 | 0 | 0.00 |
| Temp. Cycle | 620 | 185 000 | - 65 °C to 150 °C | 0 | 0.00 |